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REVISIONS

ZONE	REV	DESCRIPTION	DATE	APPROVED

NOTES:

1. PRINTED CIRCUIT BOARD IS SHOWN VIEWED FROM COMPONENT SIDE.

2. ALL MATERIALS TO BE ROHS COMPLIANT.

3. FABRICATE PER IPC-6012 AND IPC-6011. INSPECT TO IPC-A-600.

4. BOARD MATERIAL: ROHS COMPLIANT FR-4, LAMINATED SHEET, HTE COPPER CLAD, TYPE GF/GFG, WOVEN GLASS BASE, FLAME RESISTANT, MEETING UL-94V0 OR BETTER. Tg RATING OF 130 DEGREES C OR GREATER. Td RATING OF 340 DEGREES C OR GREATERMATERIAL IN ACCORDANCE WITH IPC-4101.

5. FINISH:

A. PLATED HOLES SHALL HAVE A MINIMUM COPPER THICKNESS OF .0008 IN. AND HAVE A MINIMUM OF 80% COVERAGE.

B. LPI SOLDERMASK PER IPC-SM-840 OVER BARE COPPER (SMOBC). SOLDERMASK REGISTRATION TO BE WITHIN +/- .003 OF IT'S RESPECTIVE CIRCUIT LAYER, NO MASK ON PADS.

C. PLATING TO BE ROHS COMPLIANT, IMMERSION SILVER, PER IPC-4553.

D. HOLE DIMENSIONS APPLY AFTER FINISHING.

E. HOLE TOLERANCE; +/- .003 PLATED AND +/- .005 NON-PLATED. HOLES .018 AND UNDER MAY BE PLUGGED.

6. SILKSCREEN WITH ROHS COMPLIANT WHITE NON-CONDUCTIVE INK, NO INK ON PADS. UL RECOGNIZED VENDOR MARK AND 94V-0 TO APPEAR ON SOLDERSIDE IN ETCH, ROHS COMPLIANT WHITE NON-CONDUCTIVE INK OR LASER MARKING. ROHS COMPLIANT SYMBOL TO APPEAR ON SOLDERSIDE IN ROHS COMPLIANT WHITE NON-CONDUCTIVE INK ONLY.

7. WRAP AND TWIST NOT TO EXCEED .010 IN./IN. FOR COPPER WEIGHT AND BOARD THICKNESS SEE DETAIL 'A'. LAYER TO LAYER REGISTRATION .005 IN.

8. SEE "STACKUP" DETAIL FOR COPPER WEIGHT AND BOARD THICKNESS

9. LAYER TO LAYER REGISTRATION .005 IN.

SIZE	QTY	SYM	PLATED	TOL
40	23	+	YES	+/-0.0
36	6	X	YES	+/-0.0
35	2	□	YES	+/-0.0
20	36	◇	YES	+/-0.0

3368mil

2628mil

DETAIL "A"

TOP SILKSCREEN

TOP SOLDERMASK

TOP (COMPONENT) – 1.0 oz

Adjust Thickness

BOTTOM – 1.0 oz

BOTTOM SOLDERMASK

0.062

+/- 10%

STACKUP

FILENAME	UNLESS OTHERWISE SPECIFIED	ON Semiconductor			
NCP3011_REV3_SST.pho;	DIMENSIONS ARE IN INCHES TOLERANCES ON; 2 PL DECIMALS +/- .005 3 PL DECIMALS +/- .015 ANGLES +/- 1.0 DEGREE	<div>ON Semiconductor</div> <div>NCP3011 – 2 Layer 2 Sided FABRICATION DRAWING</div>			
NCP3011_REV3_SMT.pho;					
NCP3011_REV3_TOP.pho;					
NCP3011_REV3_BOT.pho					
NCP3011_REV3_SMB.pho;					
NCP3011_REV3_DRILL.drl;					
NCP3011_REV3_DRILL.lst	DRAWN BY	SIZE	FSCM NO	DWG NO	REV
NCP3011_REV3_DRILL.rep	J. Hill			NCP3011_EVB	3
	REVISED	SCALE	NA	SHEET	1 OF 1
	02/15/2010				

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